ASSOCIATION CO	CONNECTING © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under beinternational and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility									sembly with low responsibility.	
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					eous Materia	als and Mi	g Informati	on		
upplier I	nformation														
Company name* Company unic				ique ID Uniqu			Jnique ID Authority					Response Date*			
onsemi												2024-04-23			
Contact Nam	ne		Title - Contact]	Phone - Contact*					Email - Contact*			
Product-Env	v-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized F	Representative*		Title - Representative]	Phone - Representative*				Email - Representative*				
roduct-Env	v-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
R			n Number Mfr Item Name				Effective Date	e Versi	ion	Manufacturing Site		V	Veight*	UOM	Unit Type
			ANA 3.3V 3A PW	3.3V 3A PWR SW REG			2024-04-23 MY1		MY1	(Y1		960.42	mg	Each	
Ianufactu	uring Proccess Information	on													
Те	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperatur		re Max Time at Peak Tempera		Temperat	ire Numb	er of Reflow Cyc	les		
Matte Tin (Sn) - annealed		С	CU Alloy NA			0 C		30 see		second	ls 3				
omments															
or more inf	formation regarding material co	omposition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

	cable [E] enter the weigh			ance category (JIG or Requester) or enter [F] Optionally enter the positive (+) and				
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.83	mg	А	Lead (Pb)	7439-92-1	7a	78.6885	mg
			Supplier	Tin (Sn)	7440-31-5		4.1415	mg
Lead Frame	1297.64	mg	Supplier	Copper (Cu)	7440-50-8		1297.64	mg
Mold Compound-Black	543.9	mg		Epoxy resin	proprietary data		38.073	mg
			Supplier	Phenolic Resin	Proprietary Data		38.073	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		81.585	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		383.4495	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg